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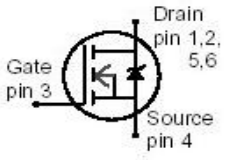
OptiMOS®2 Small-Signal-Transistor

Features

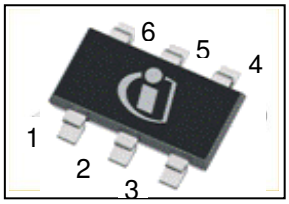
- N-channel
- Enhancement mode
- Logic level (4.5V rated)
- Avalanche rated
- d*v*/d*t* rated
- Pb-free lead plating; RoHS compliant
- Qualified according to AEC Q101
- Halogen free according to IEC61249-2-21

Product Summary

V_{DS}		30	V
$R_{DS(on),max}$	V_{GS}=10 V	25	mΩ
	V_{GS}=4.5 V	38	
I_D		7.1	A



PG-TSOP-6



Type	Package	Tape and Reel Information	Marking	Lead Free	Packing
BSL302SN	PG-TSOP-6	H6327 = 3000 pcs. / reel	sPE	Yes	Non dry

Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	T_A=25 °C	7.1	A
		T_A=70 °C	5.7	
Pulsed drain current	$I_{D,pulse}$	T_A=25 °C	28	
Avalanche energy, single pulse	E_{AS}	I_D=7.1 A, R_{GS}=25 Ω	30	mJ
Reverse diode d*v*/d*t*	d*v*/d*t*	I_D=7.5 A, V_{DS}=16 V, d*i*/d*t*=200 A/µs, $T_{j,max}$=150 °C	6	kV/µs
Gate source voltage	V_{GS}		±20	V
Power dissipation[1)]	P_{tot}	T_A=25 °C	2	W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150	°C
ESD Class		JESD22-A114-HBM	0 (0V to 250V)	
Soldering Temperature			260 °C	
IEC climatic category; DIN IEC 68-1			55/150/56	

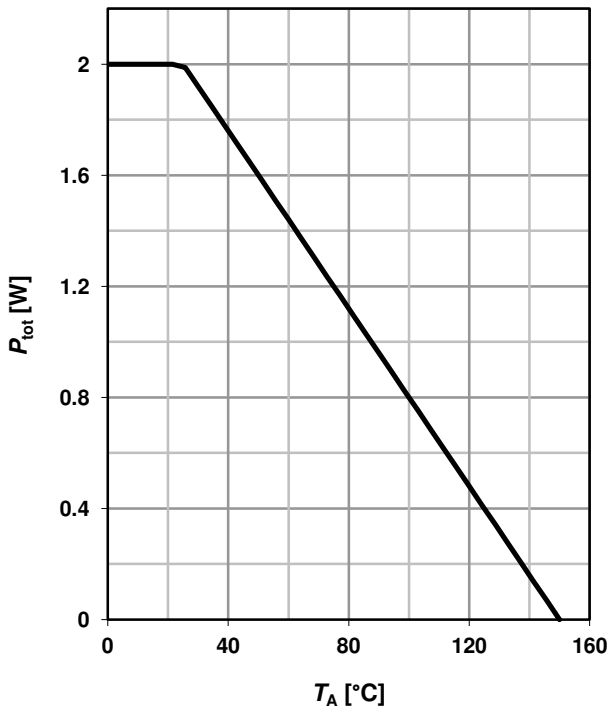
Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics						
Thermal resistance, junction - minimal footprint	R_{thJS}		-	-	50	K/W
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	230	
		6 cm^2 cooling area[1)]	-	-	62.5	
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D=250 µA	30	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=30 µA	1.2	1.70	2	
Drain-source leakage current	I_{DSS}	V_{DS}=20 V, V_{GS}=0 V, T_j=25 °C	-	-	1	µA
		V_{DS}=20 V, V_{GS}=0 V, T_j=150 °C	-	-	100	
Gate-source leakage current	I_{GSS}	V_{GS}=20 V, V_{DS}=0 V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=4.5 V, I_D=5.7 A	-	27	38	mΩ
		V_{GS}=10 V, I_D=7.1 A	-	18	25	
Transconductance	g_{fs}	$\|V_{DS}\|>2\|I_D\|R_{DS(on)max}$, I_D=7.1 A		16	-	S

[1)] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (single layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air. (t < 5 sec.)

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics						
Input capacitance	C_{iss}	V_{GS}=0 V, V_{DS}=15 V, f=1 MHz	-	564	750	pF
Output capacitance	C_{oss}		-	202	269	
Reverse transfer capacitance	C_{rss}		-	28	43	
Turn-on delay time	$t_{d(on)}$	V_{DD}=15 V, V_{GS}=10 V, I_D=7.1 A, $R_{G,ext}$=1.6 Ω	-	6.4	-	ns
Rise time	t_r		-	2.8	-	
Turn-off delay time	$t_{d(off)}$		-	13.7	-	
Fall time	t_f		-	1.9	-	
Gate Charge Characteristics						
Gate to source charge	Q_{gs}	V_{DD}=15 V, I_D=7.1 A, V_{GS}=0 to 5 V	-	1.78	2.37	nC
Gate to drain charge	Q_{gd}		-	1.2	1.8	
Gate charge total	Q_g		-	4.4	6.6	
Gate plateau voltage	$V_{plateau}$		-	3.2	-	V
Reverse Diode						
Diode continous forward current	I_S	T_A=25 °C	-	-	2.5	A
Diode pulse current	$I_{S,pulse}$		-	-	28	
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=7.1 A, T_j=25 °C	-	0.8	1.2	V
Reverse recovery time	t_{rr}	V_R=15 V, I_F=7.1 A, di_F/dt=100 A/µs	-	14.2		ns
Reverse recovery charge	Q_{rr}		-	5.1	-	nC

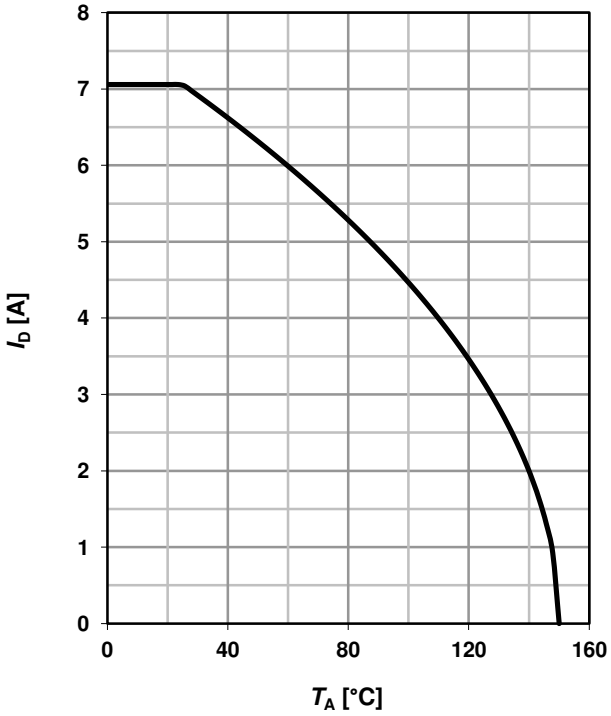
1 Power dissipation

$P_{tot}=f(T_A)$



2 Drain current

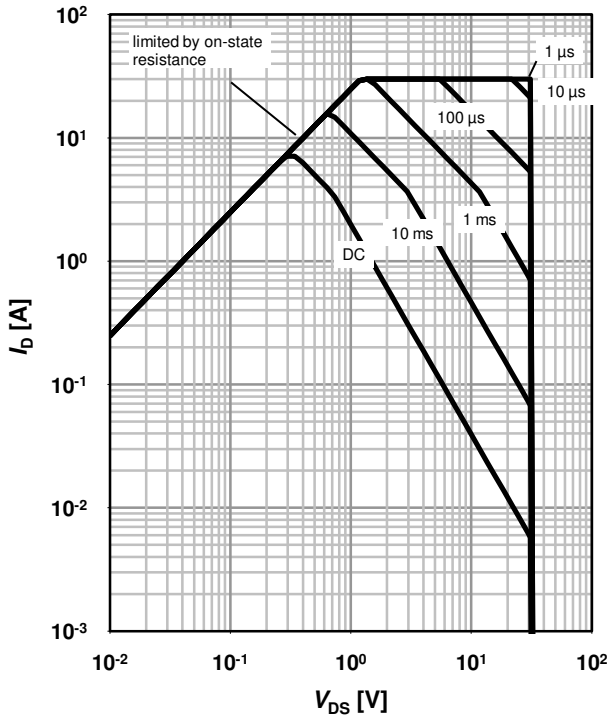
$I_D=f(T_A)$; $V_{GS}\geq 10$ V



3 Safe operating area

$I_D=f(V_{DS})$; $T_A=25$ °C; $D=0$

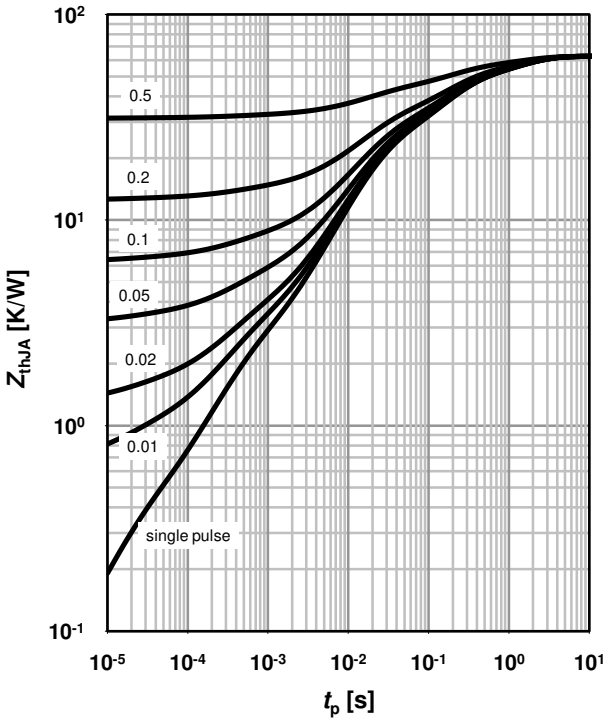
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJA}=f(t_p)$

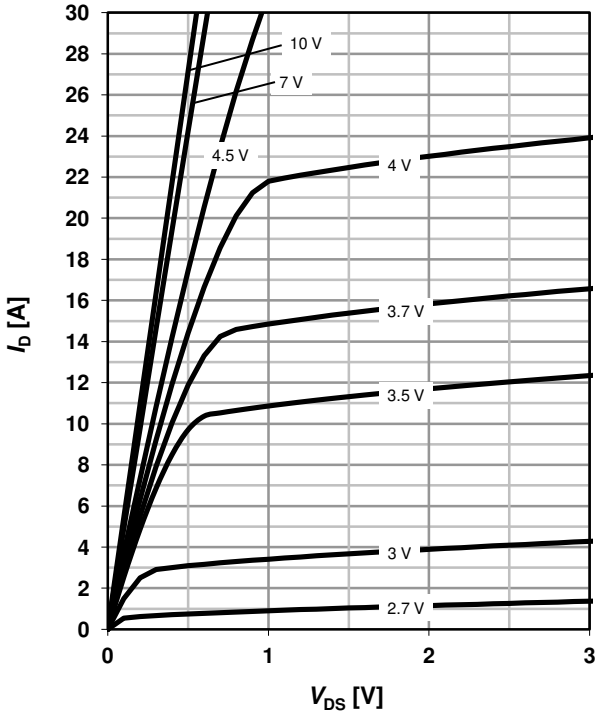
parameter: $D=t_p/T$



5 Typ. output characteristics

I_D=f(V_{DS}); T_j=25 °C

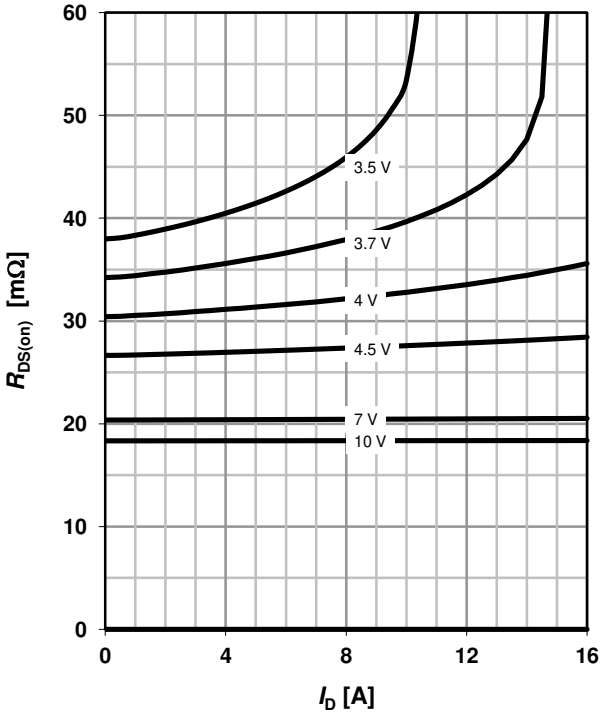
parameter: V_{GS}



6 Typ. drain-source on resistance

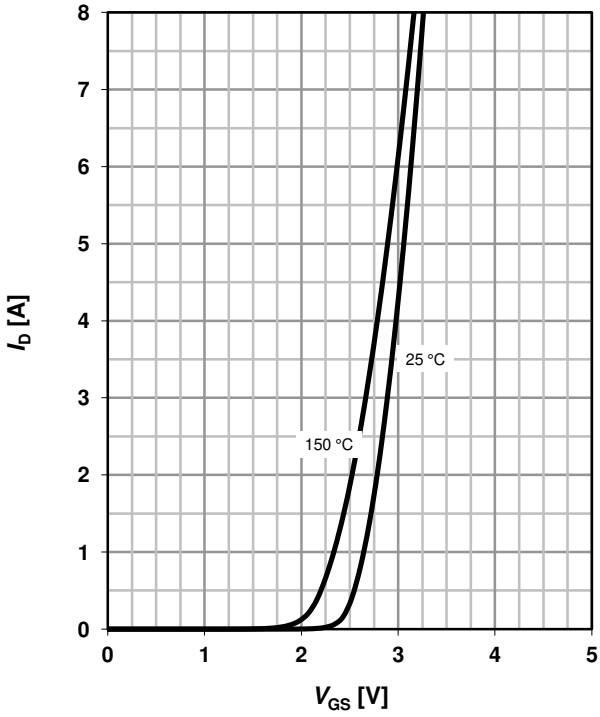
$R_{DS(on)}$=f(I_D); T_j=25 °C

parameter: V_{GS}

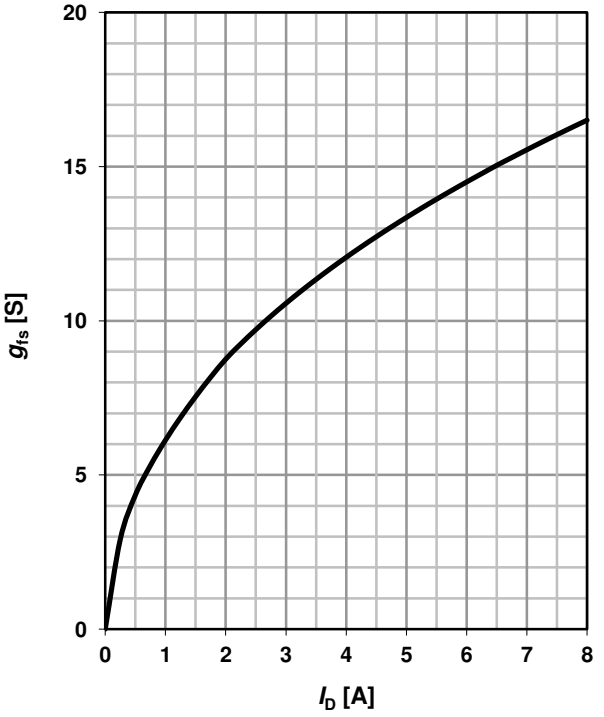


8 Typ. forward transconductance

I_D=f(V_{GS}); $|V_{DS}|>2|I_D|R_{DS(on)max}$

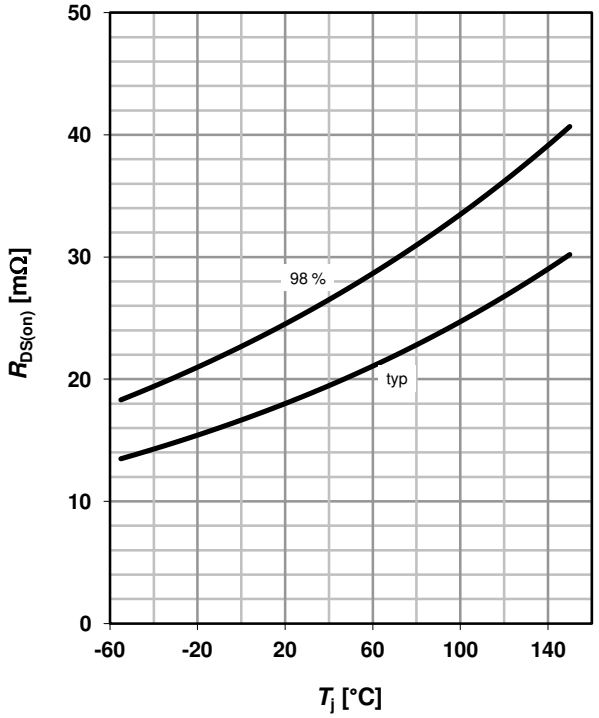


g_{fs}=f(I_D); T_j=25 °C



9 Drain-source on-state resistance

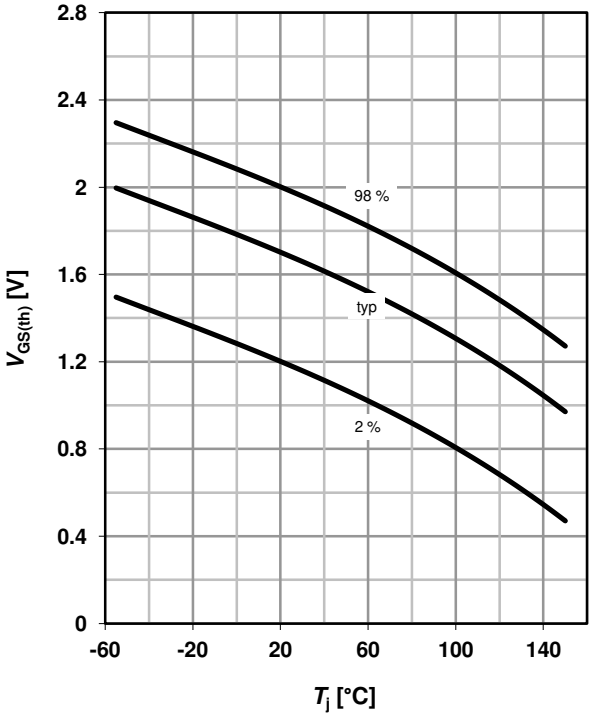
$R_{DS(on)}$=f(T_j); I_D=7.1 A; V_{GS}=10 V



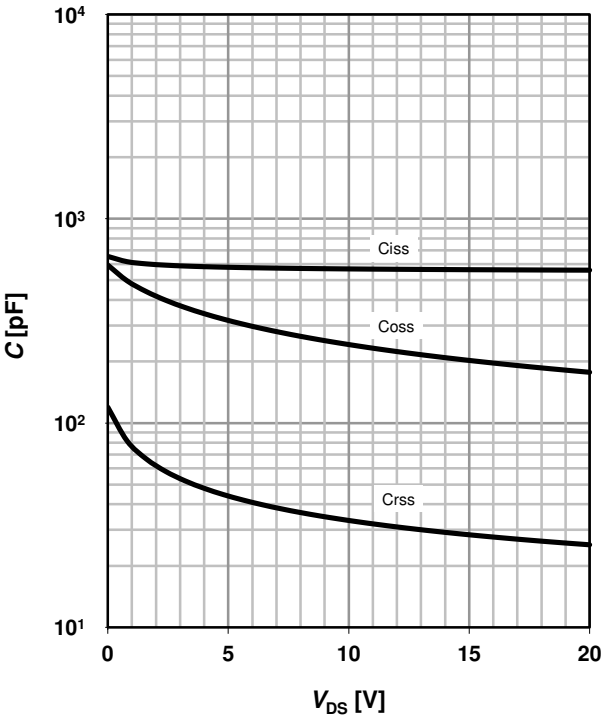
10 Typ. gate threshold voltage

$V_{GS(th)}$=f(T_j); V_{DS}=V_{GS}; I_D=30 µA

parameter: I_D



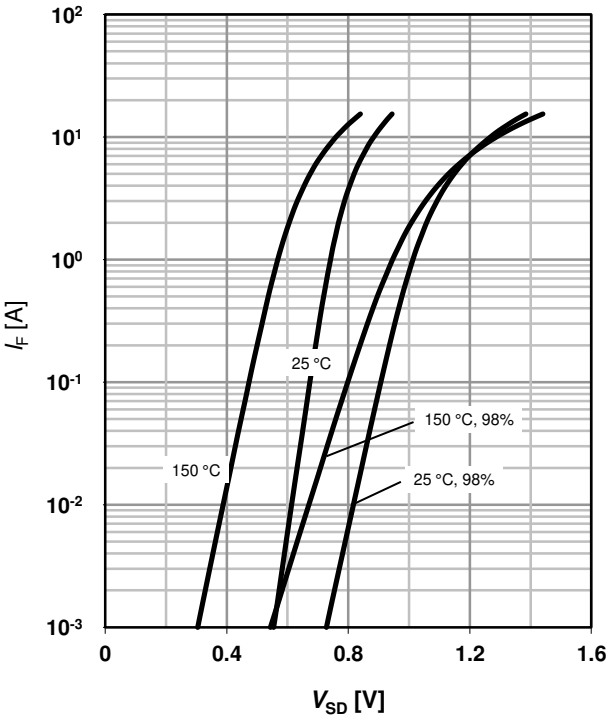
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz; T_j=25°C



12 Forward characteristics of reverse diode

I_F=f(V_{SD})

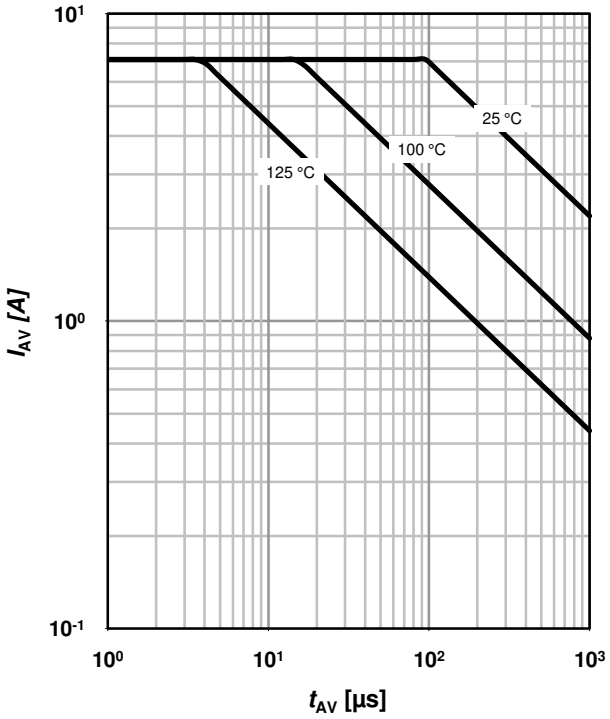
parameter: T_j



13 Avalanche characteristics

I_{AS}=f(t_{AV}); R_{GS}=25 Ω

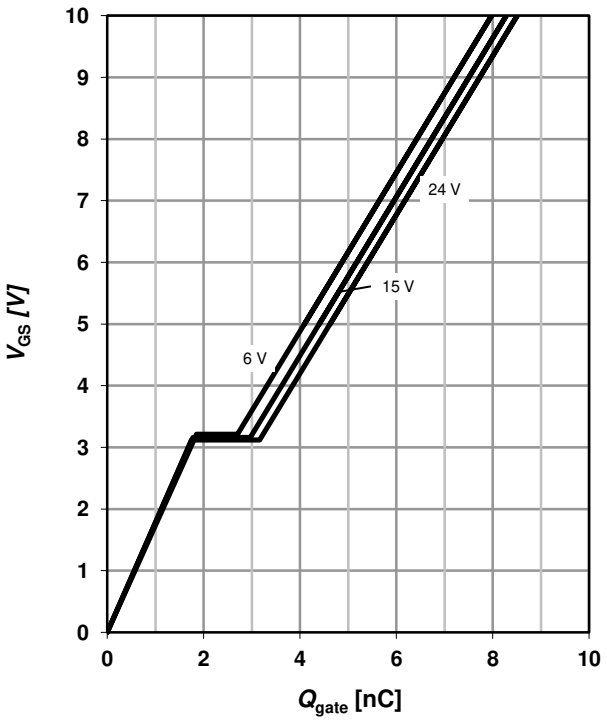
parameter: $T_{j(start)}$



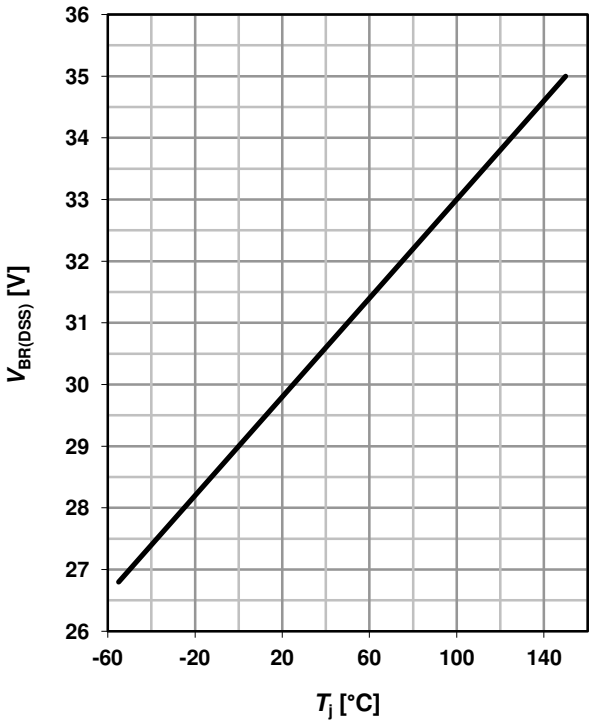
14 Typ. gate charge

V_{GS}=f(Q_{gate}); I_D=7.1 A pulsed

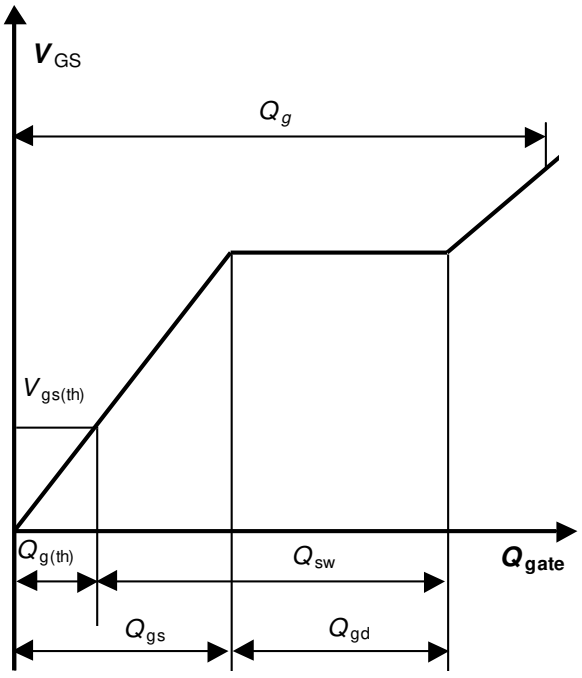
parameter: V_{DD}



$V_{BR(DSS)}$=f(T_j); I_D=250 µA

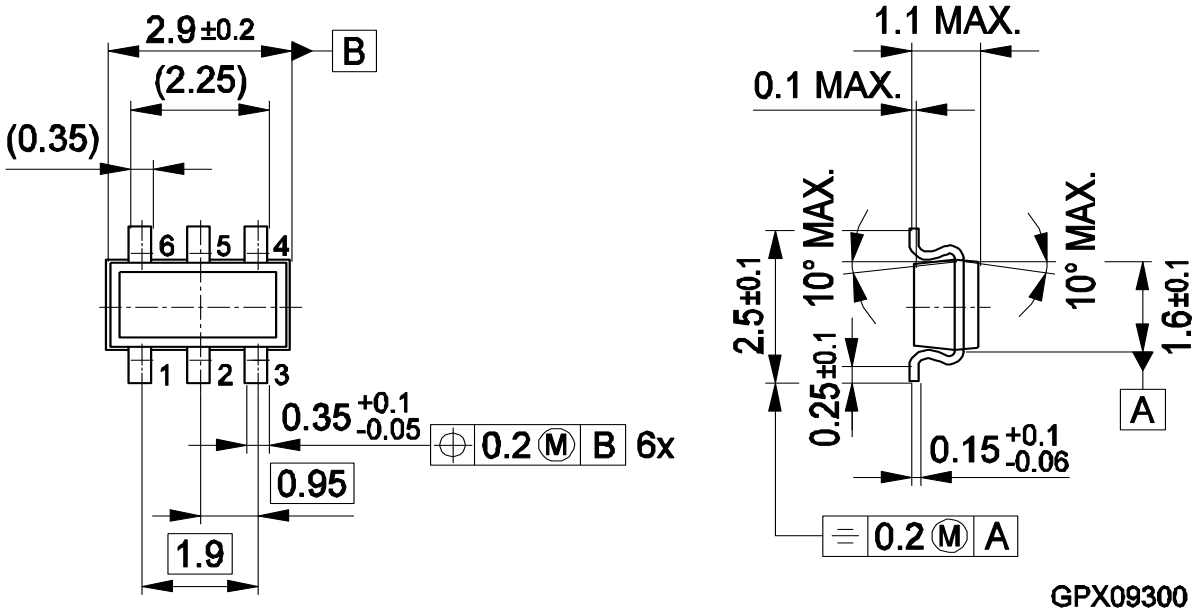


16 Gate charge waveforms

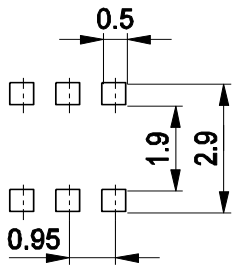


Package Outline:

TSOP6



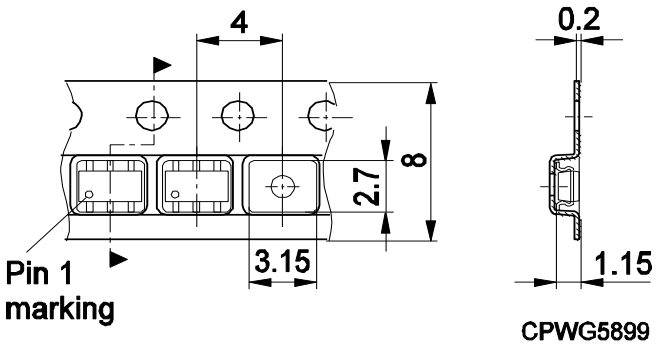
Footprint:



Remark: Wave soldering possible dep. on customers process conditions

HLG09283

Packaging:



Dimensions in mm

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